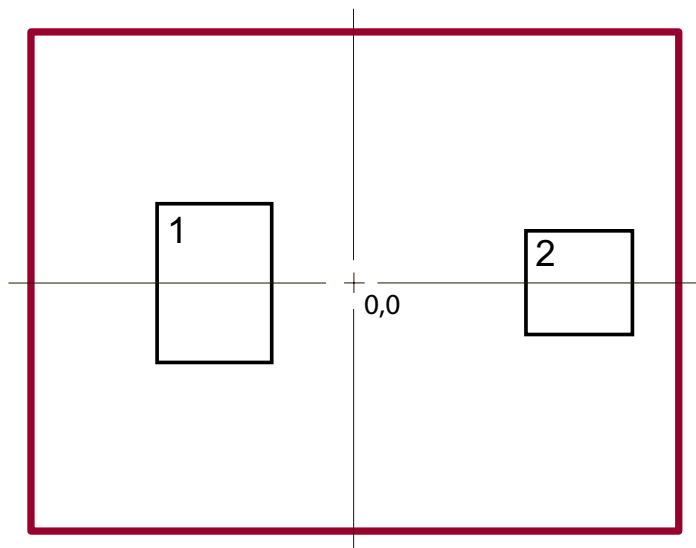


Pad Layout



Die Specifications

Die Dimensions (mils)			Die Dimensions (µm)			Back Side Metal	Back Side	Bonding Pad Material
Length ¹	Width ¹	Thickness	Length ¹	Width ¹	Thickness			
50.00	64.57	9.49 - 12.52	1270	1640	241 - 318	Au	Drain	Al/Cu/Si

Pad Descriptions

Pad #	Function	x Position ² (µm)	y Position ² (µm)	x Size (µm)	y Size (µm)
1	Source	-349.3	0	321.5	400
2	Gate	553.1	0	253.8	260

Notes:

1. Maximum values.
2. Position referenced to center of pad.

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